

AMENDMENT

CLAIMS

1. (Amended) A resin plating method with an added heat-treating process for a resin molding, in which resin plating is performed after a specific portion of the resin molding which portion is apt to undergo peeling of a thin surface resin film of the resin molding is heat-treated at a high temperature.

2. (Deleted)

3. A resin plating method with an added heat-treating process according to claim 1,

wherein the resin molding is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retains a generally circular shape.

4. A resin plating method with an added heat-treating process according to claim 1,

wherein the resin molding is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

5. (Amended) A resin plating method with an added heat-treating process according to any of claims 1, 3 and 4,

wherein a parting line portion of the resin molding is heat-treated at a high temperature.

6. (Deleted)

7. (Deleted)

8. A resin plating method with an added heat-treating process according to claim 5,

wherein in the case where the resin molding is formed of ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding a surface temperature range of the resin molding of 80° to 150°C.

9. A resin plating method with an added heat-treating process according to claim 5,

wherein in the case where the resin molding is formed of PC/ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding to a surface temperature range of the resin molding of 100° to 200°C.

10. (Deleted)